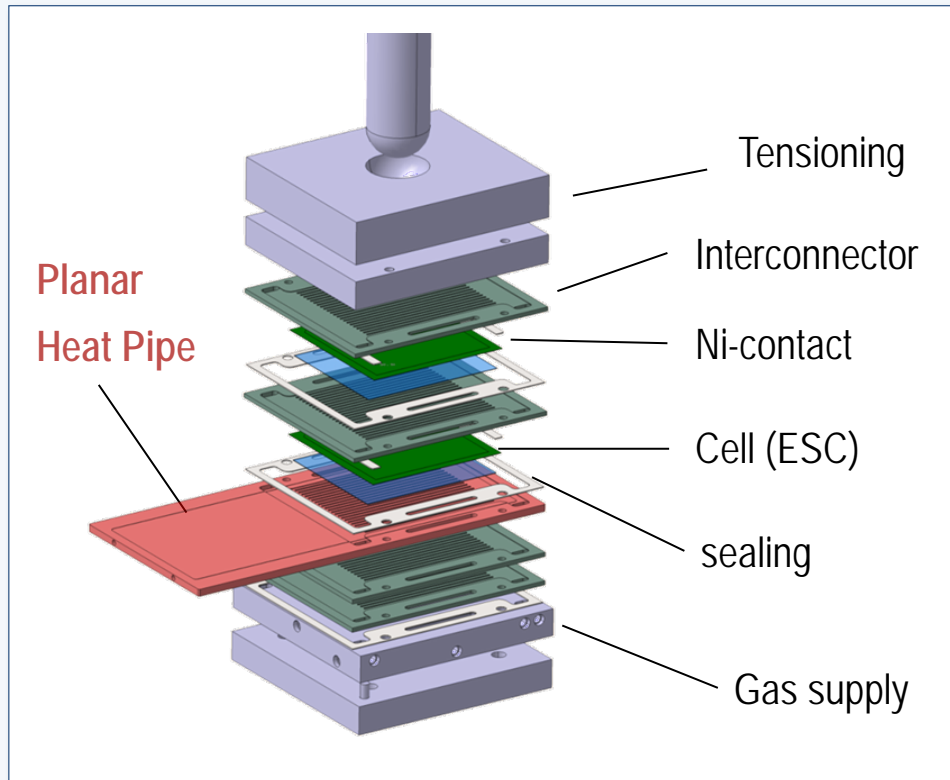


Hydrogen Days 2015, Prague, 18 - 20 March 2015

Thermal control of solid oxide electrolyser cells / fuel cells with high temperature heat pipes



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Outline

I 1. Motivation – SOFC /SOEC & Heat Pipes

- Improved thermal management
- Dynamic operation

II 2. Planar Heat Pipe development

- Heat Pipe Design
- Experimental results

III 3. Short stack design & Experiments

- Stack design and Heat Pipe integration
- First experimental results

IV 4. Conclusions



I

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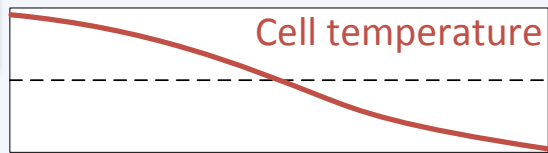
1. Motivation – SOFC & Heat Pipes

- Improved thermal management
- Dynamic operation

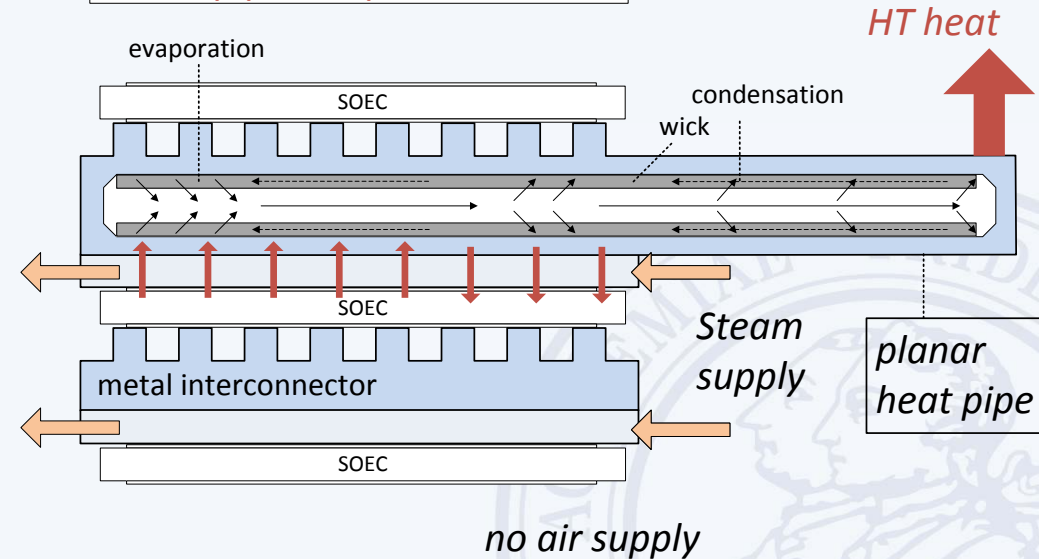
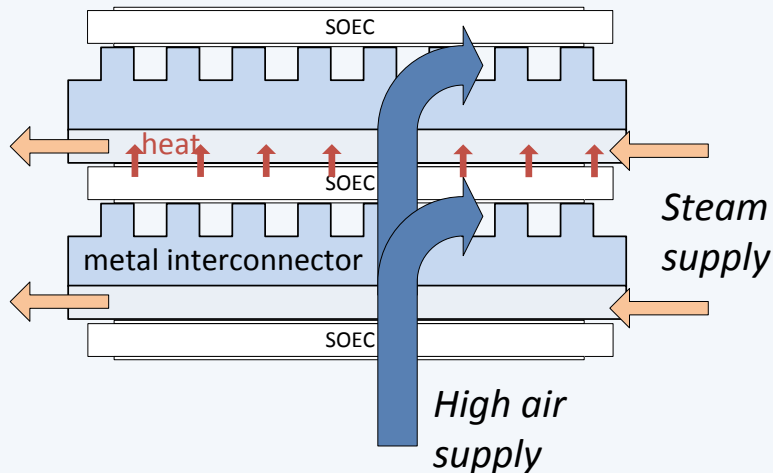
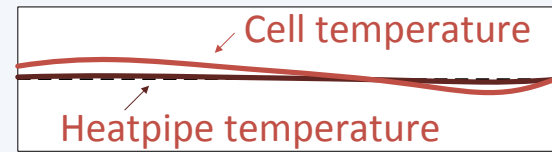


Concept – planar Heat Pipe Interconnector

no HP



with HP



2 main goals of integrated planar heat pipe:

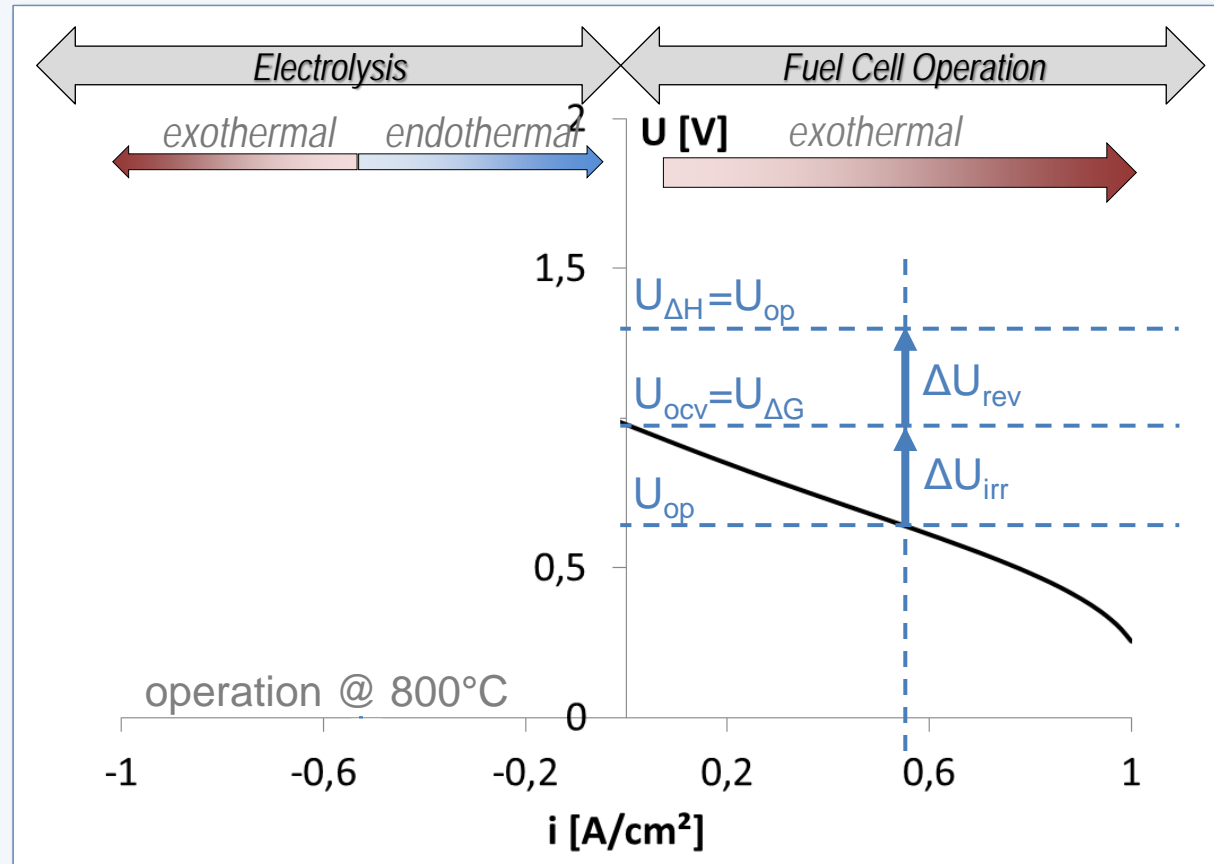
- Internal temperature gradient reduction
 - dynamic operation of stacks
 - reduction of cooling air
- Isothermal heat extraction from SOFC stack
 - high temperature heat supply to secondary processes

Load flexible SOFC / SOEC

Stack Thermal Balance:

Heat production depending on operation mode:

- Exothermal
- Endothermal
- Thermoneutral operation



Current –Voltage Diagram of Solid Oxide Cell

Load flexible SOCs

Thermal gradients in stacks in cell layer

→ Dynamic stress

→ Cell degradation:

→ Microcracking

→ Delamination

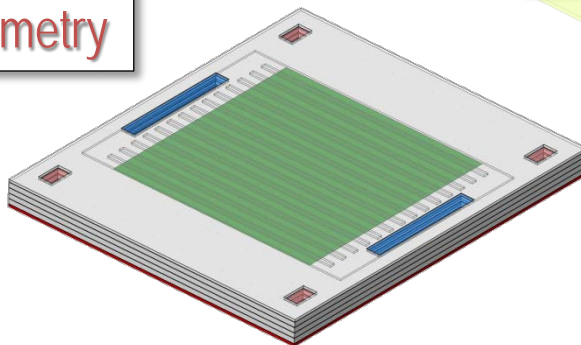
→ Sealing degradation

Heat Pipe integration:

→ Internal thermal balancing in cell layer

→ Heat supply / removal

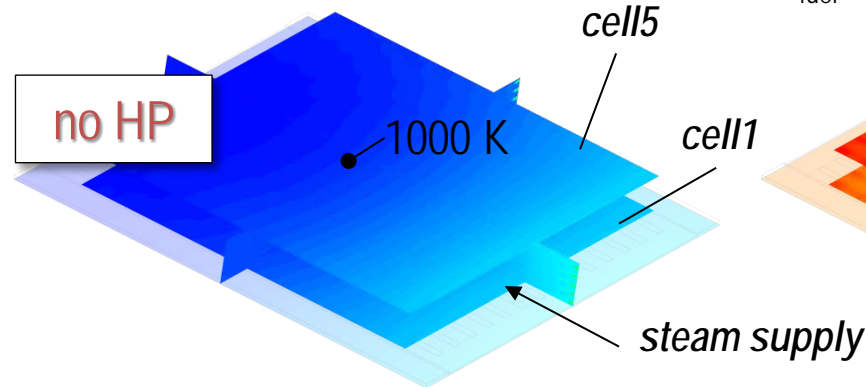
geometry



endothermal SOEC

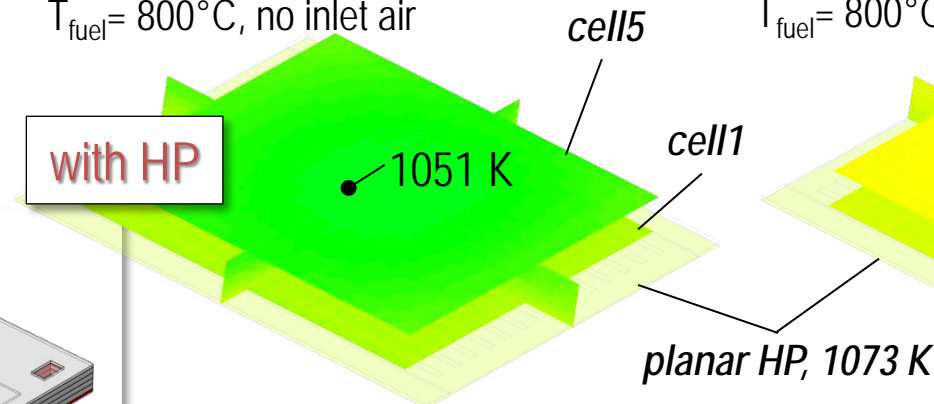
1.16 V, 0,27 A/cm², SU=0.13

T_{fuel} = 800°C, no inlet air



1.16 V, 0,43 A/cm², SU=0.28

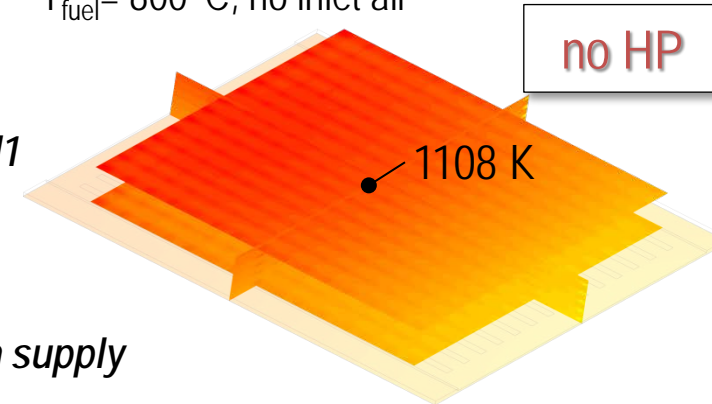
T_{fuel} = 800°C, no inlet air



exothermal SOEC

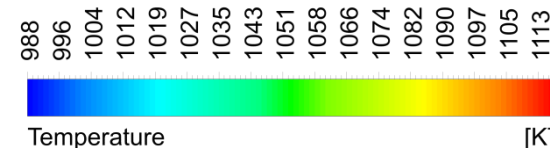
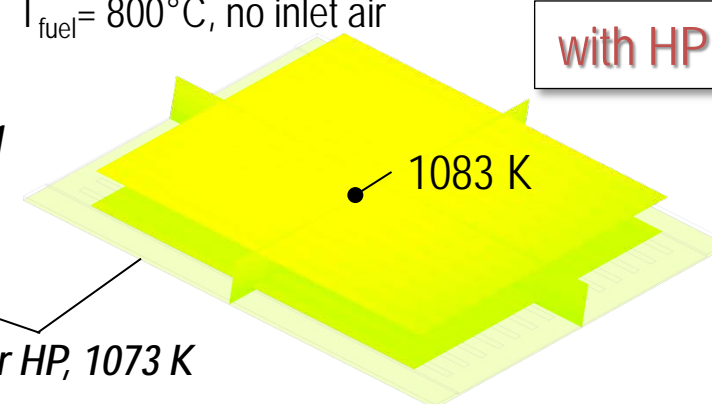
1.34 V, 0,96 A/cm², SU=0.78

T_{fuel} = 800°C, no inlet air



1.34 V, 0,82 A/cm², SU=0.78

T_{fuel} = 800°C, no inlet air



Process integration

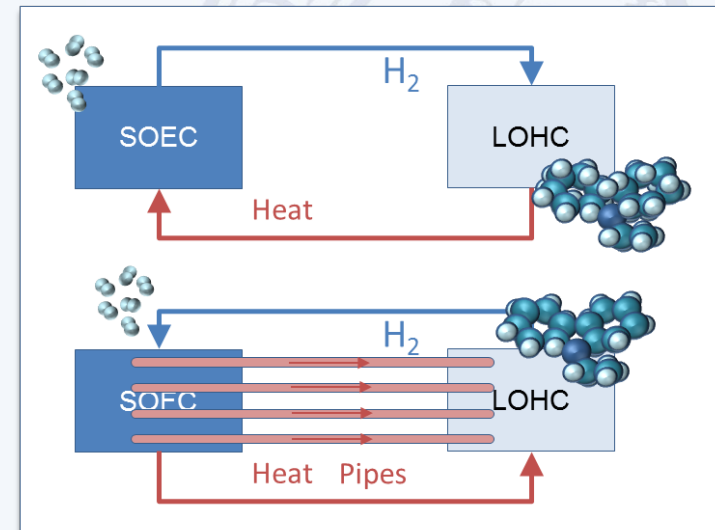
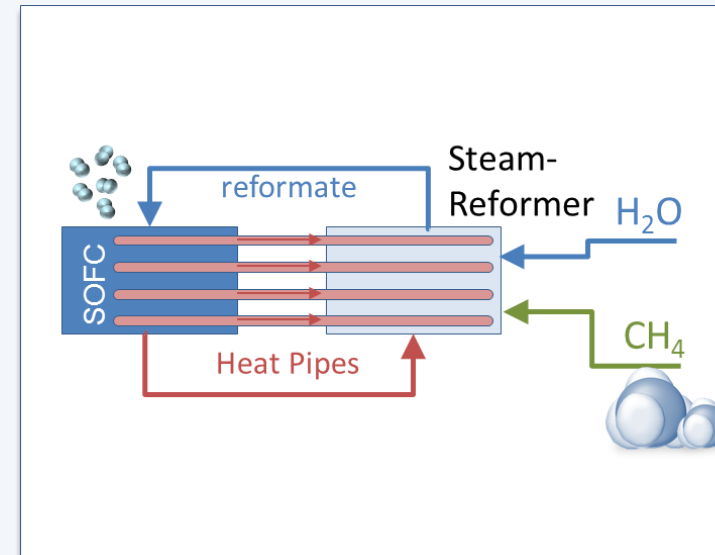
Direct thermal integration of SOFC stacks and endothermal fuel preparation:

- CH₄ (pre-) Reforming
- H₂ – release from H₂ storage media (LOHC*)

*Liquid organic hydrogen carriers:

D. Teichmann, W. Arlt, P. Wasserscheid, Int. J. Hydrogen Energy 2012, 37, 18118-18132.

SOFC / SOEC system (0,75V,AR=2)	Heat from SOFC stack [W/cm ²]	Heat demand [W/cm ²]
100% pre SR** CH ₄	0,30	0,19 (SR CH ₄)
25% pre SR CH ₄	0,14	0,05 (SR CH ₄)
H ₂ from LOHC	0,29	0,28 (LOHC)

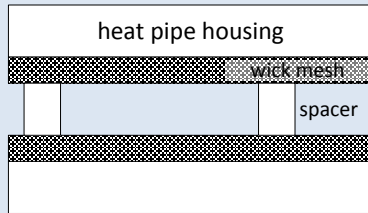


2. Planar Heat Pipe development

- Heat Pipe Design
- Experimental results

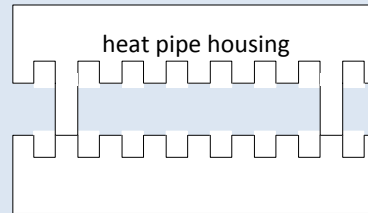


HP Interconnector: Design and production



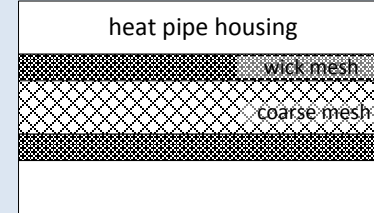
- a) Screen mesh layers as wick structure separated by spacing elements

Mesh sizes 60 - 200



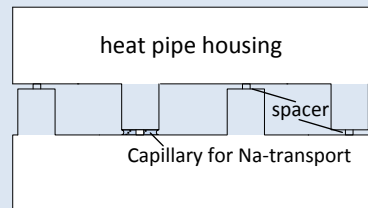
- b) Rectangular axial grooves with vapour space separators

Grooves size 200 – 500 μm



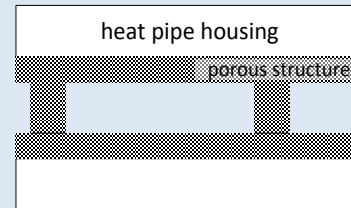
- c) Sandwich design with fine screen mesh layers as wick and coarse mesh as vapour space separator

Mesh size: 10; 60-200



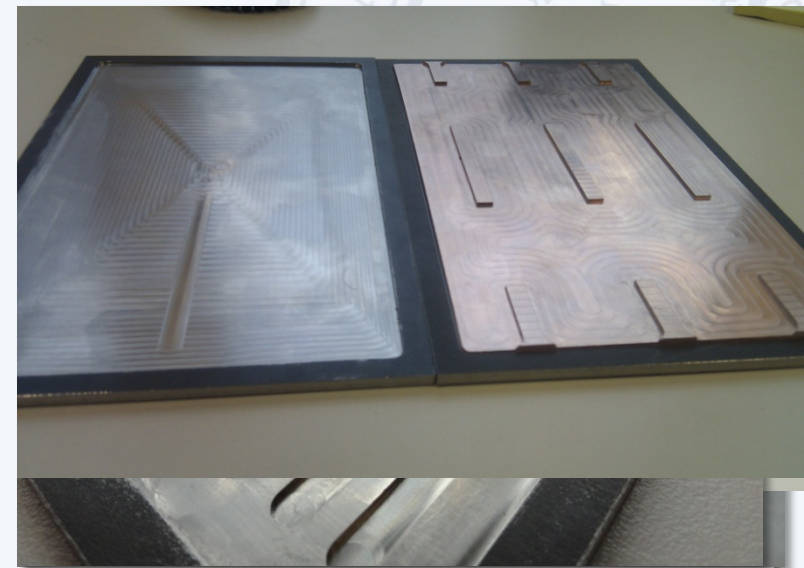
- d) Small flat housing gap as planar capillary structure

Capillary height 50 -100 μm

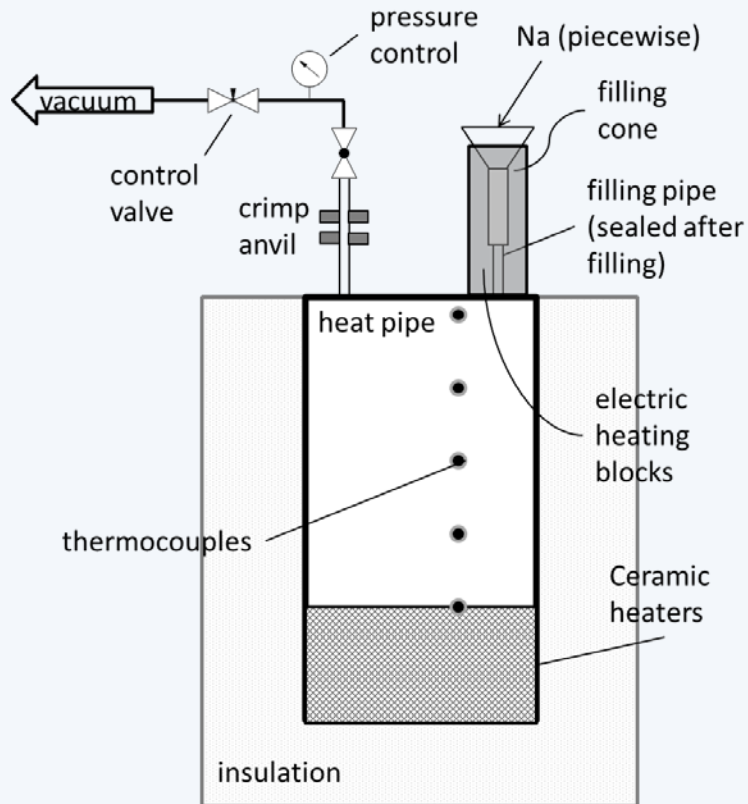


- e) Porous medium as wick structure and vapour space separator

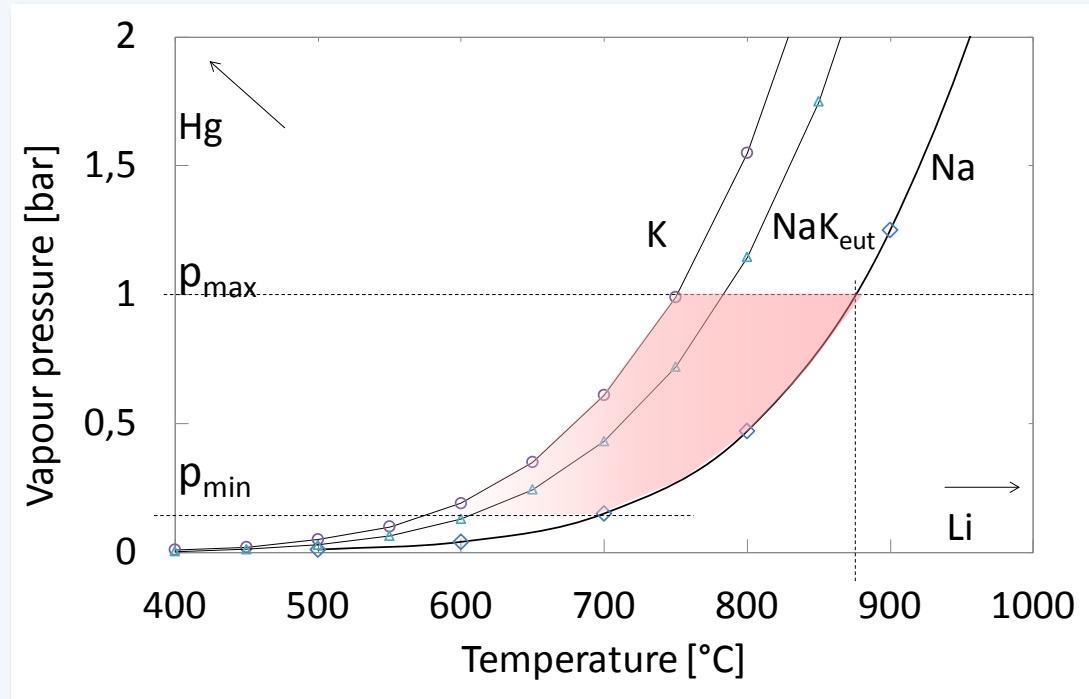
Pore sizes: ca. 50 -200 μm



HP Interconnector: Design and production



Filling and degassing procedure



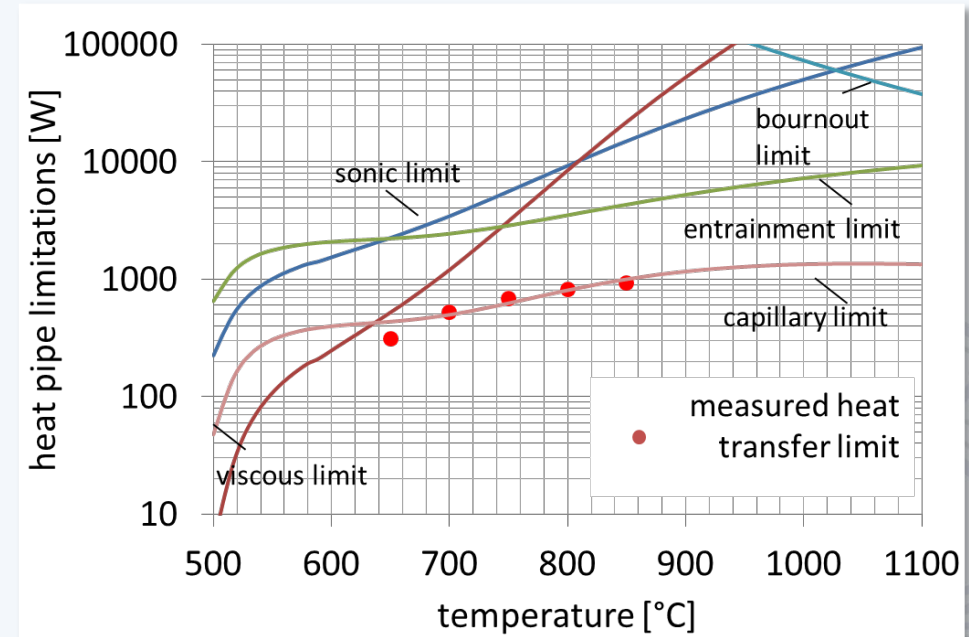
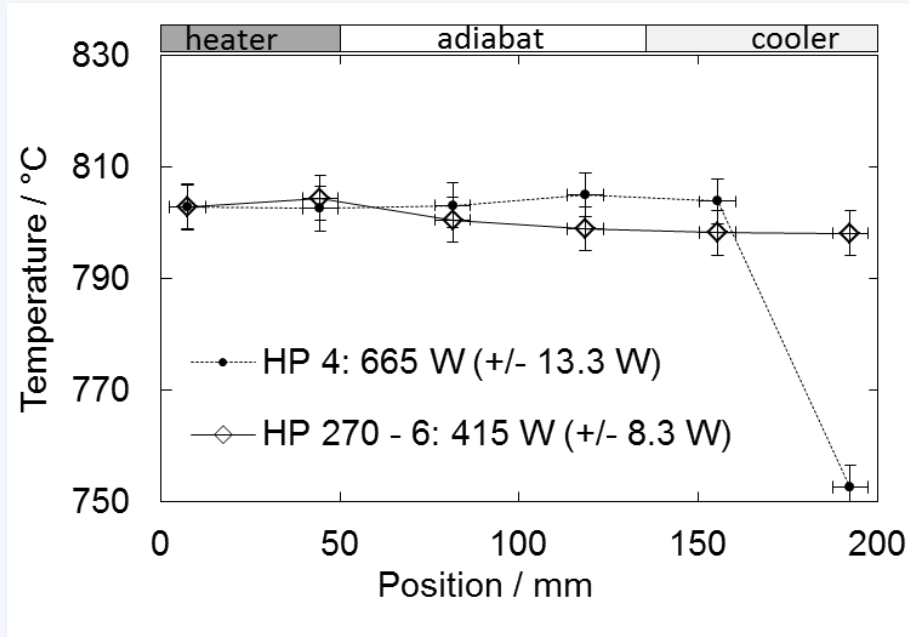
Planar high temp. Heat Pipes:

Heat transfer fluid (max $p_{sat}=1$ bar):
 → Sodium (Na) , Potassium (K) or NaK

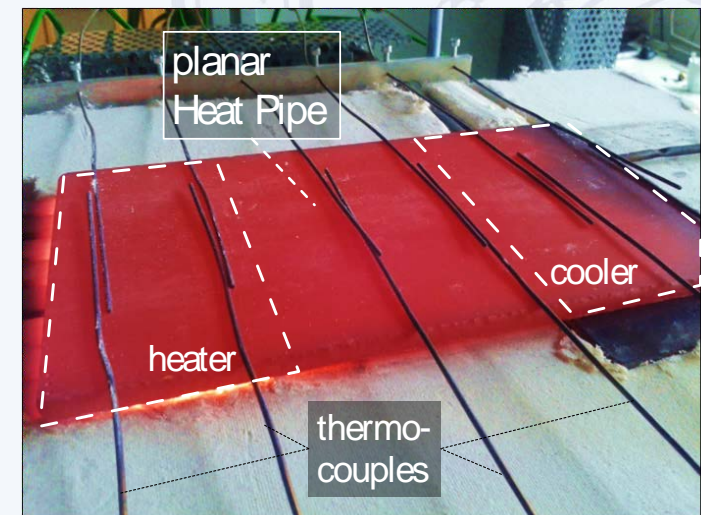
Wick material: → 1.4841

Casing: → Crofer 22H

Heat Pipe performance - results



- almost isothermal operation (only few K of dT in casing) for horizontal operation
- axial heat transfer rates up to 1000 W per planar HP (to 100 W/cm² HP cross section)
- grooved structures and pourous media still under evaluation
- screen meshed heat pipes with best results (mesh:80 | 8 | 80)



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3. Short stack design & Experiments

- Stack design and Heat Pipe integration
- First experimental results



Stack Design:

Cell:

ESC 10Sc1CeSZ

100 x 100 mm

Interconnector:

Crofer 22H

milled flow field, crossflow

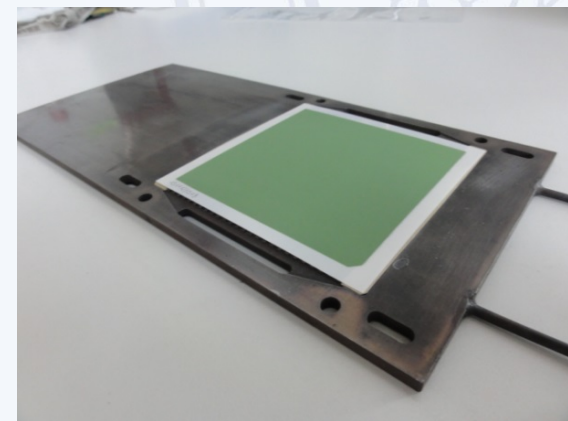
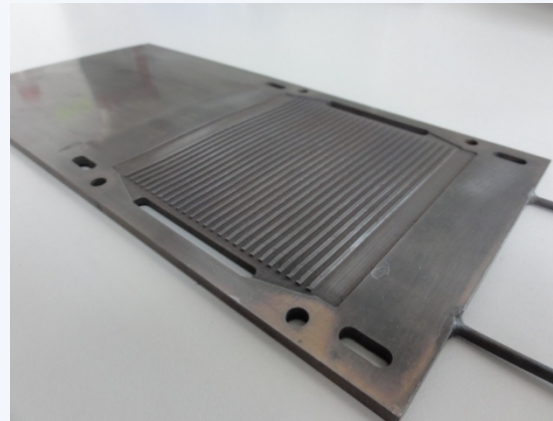
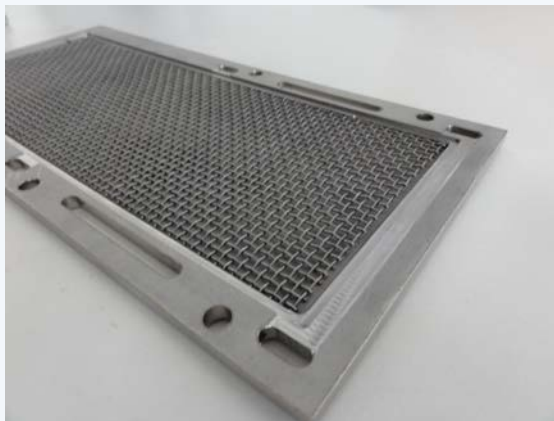
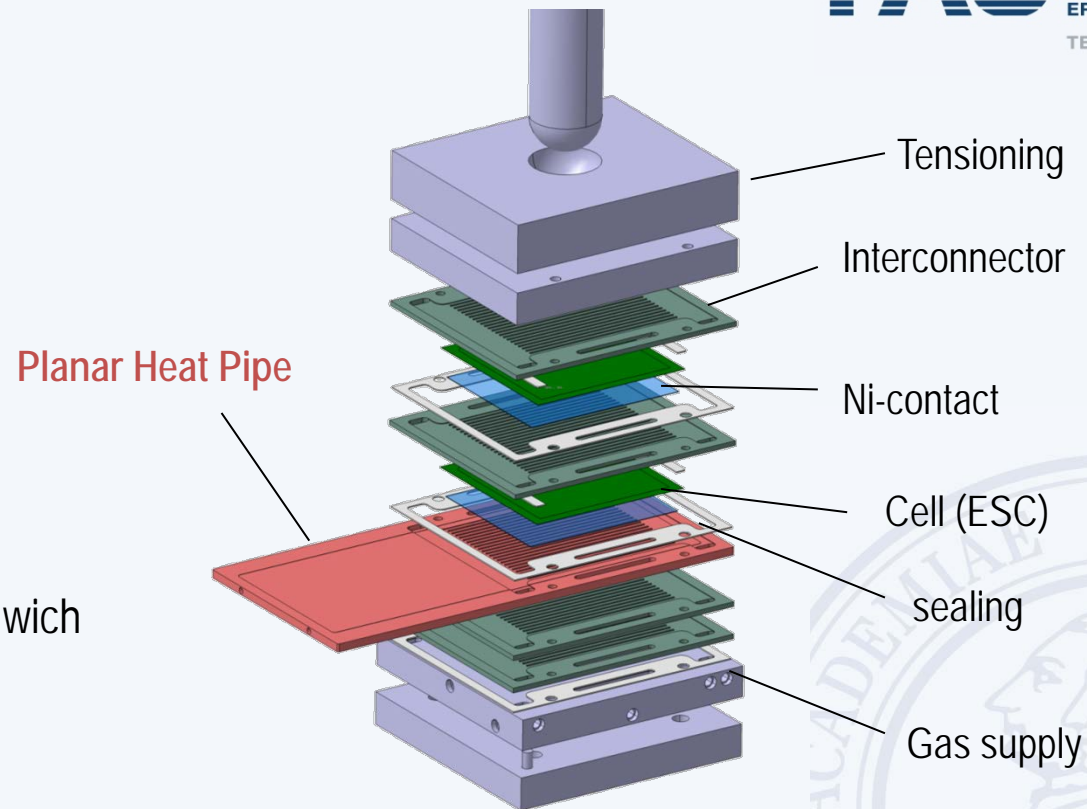
Heatpipe - Interconnector:

270 x 130 mm, t = 4 mm, Sandwich

Design (Mesh 80, 8), 1.4841

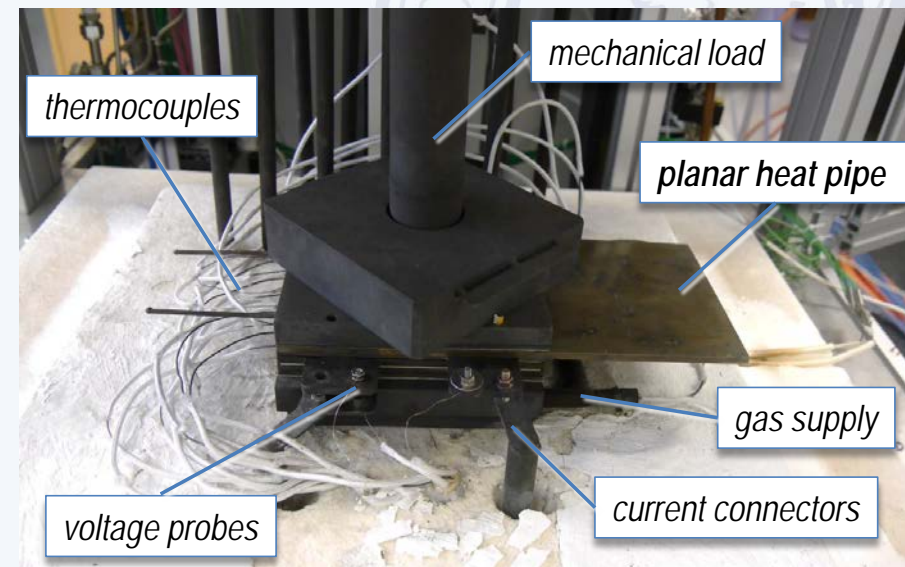
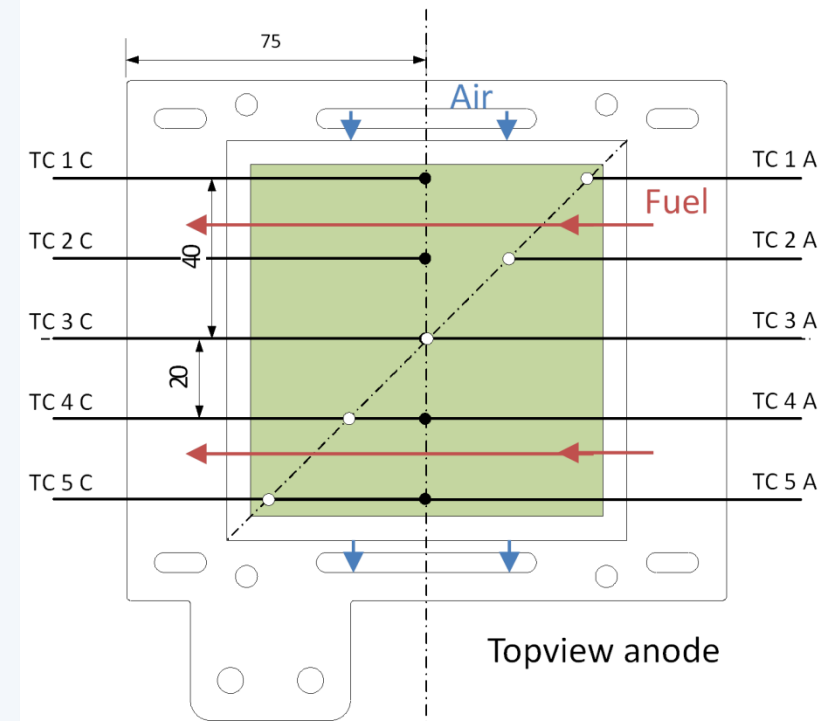
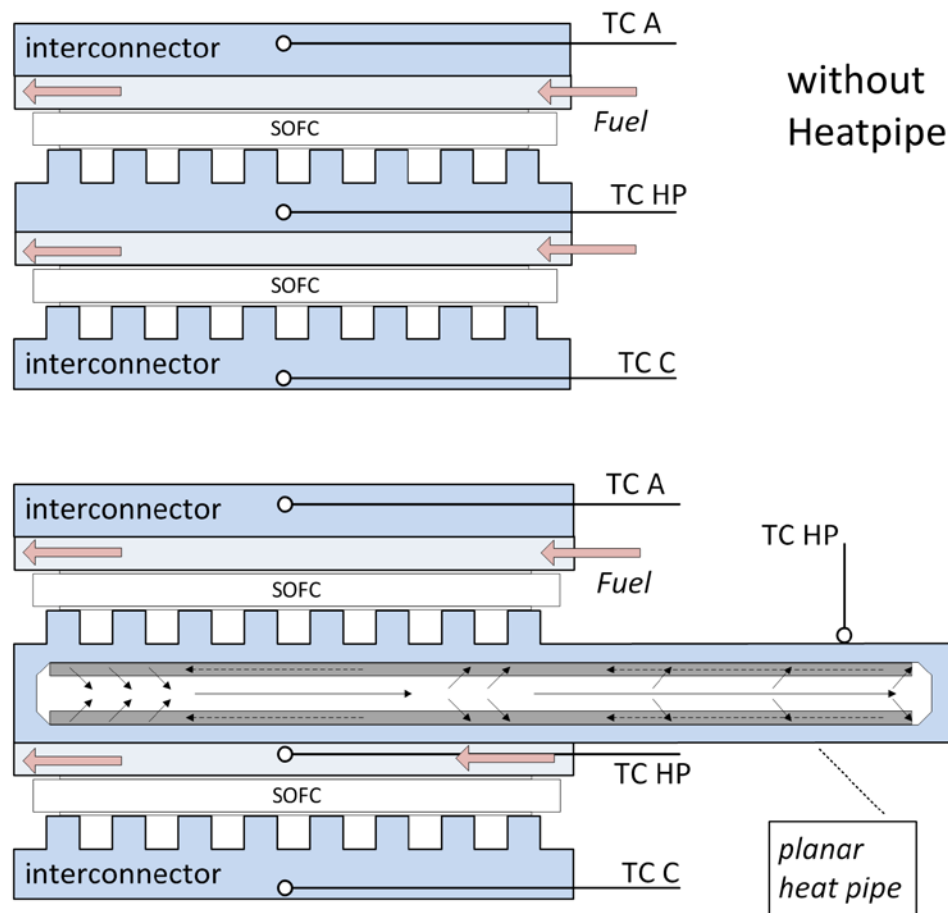
Sealing:

Thermiculite 866, 0,2-0,4 MPa



Shortstack test – set up

- 2-cell shortstack set up with integrated HP
- Placing of thermocouples within stack structure



SOFC / SOEC shortstack tests

Results:

Dynamic operation possible:

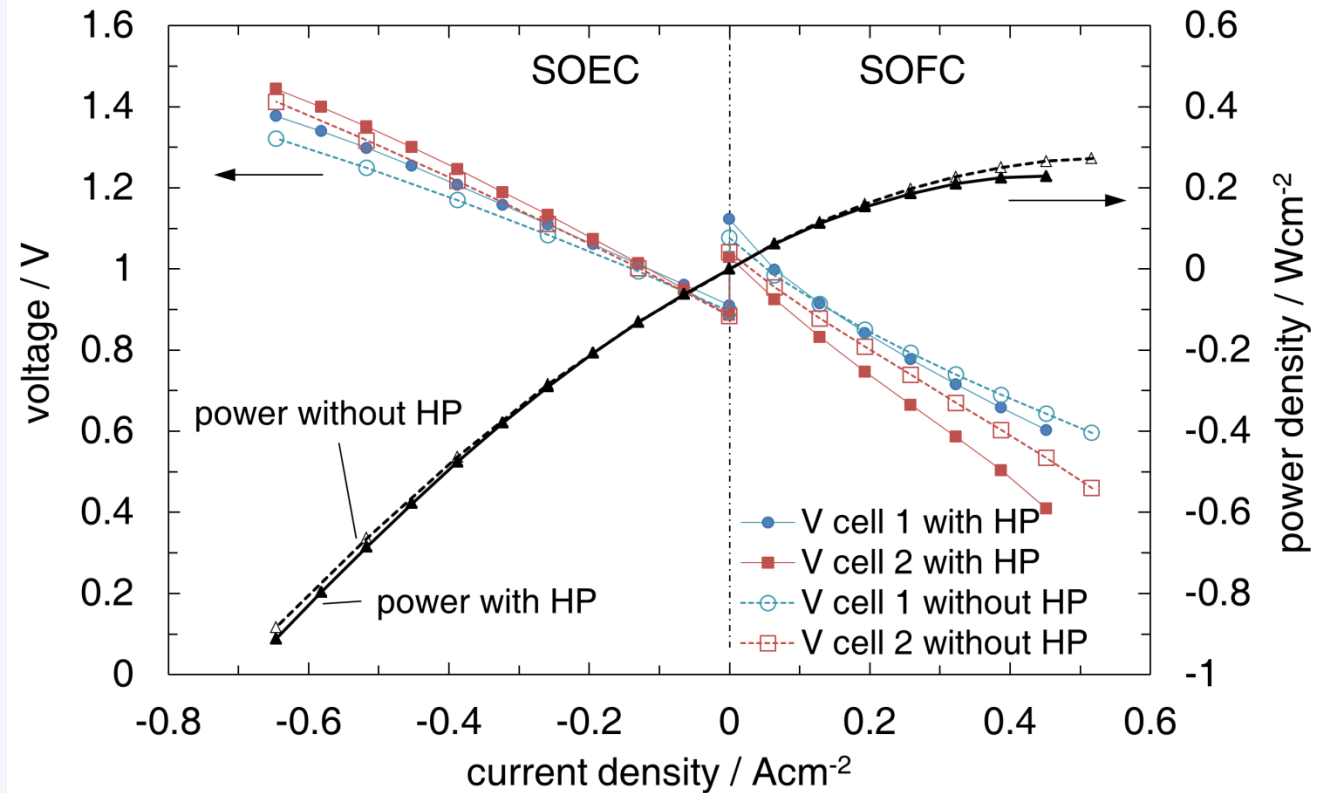
300 SOFC / SOEC cycles

SOFC: 0,20 A/cm²; 0,70 V

SOEC: 0,32 A/cm²; 1,10 V

→ differences in cell contacting due to planarity problems of „planar“ heat pipe

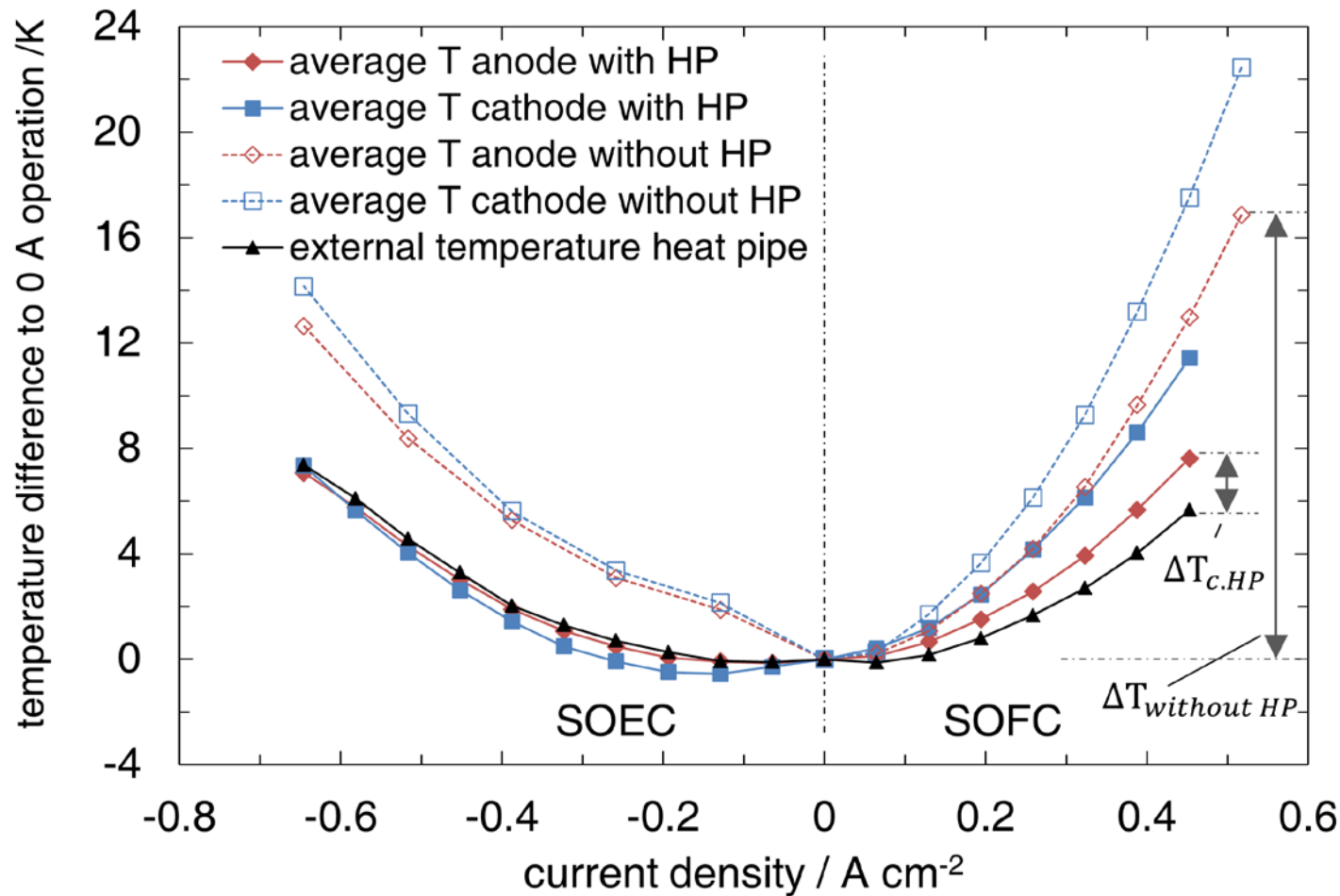
→ Sealing, Contacting to be improved



SOEC operation: 850°C, 90 g/h
 H₂O, 1.8 NI/min H₂, 3.0 NI/min Air

SOFC operation: 850°C, 1.5 NI/min
 H₂, 1.5 NI/min N₂, 3.0 NI/min Air

SOFC / SOEC 2 - cell shortstack tests with HP



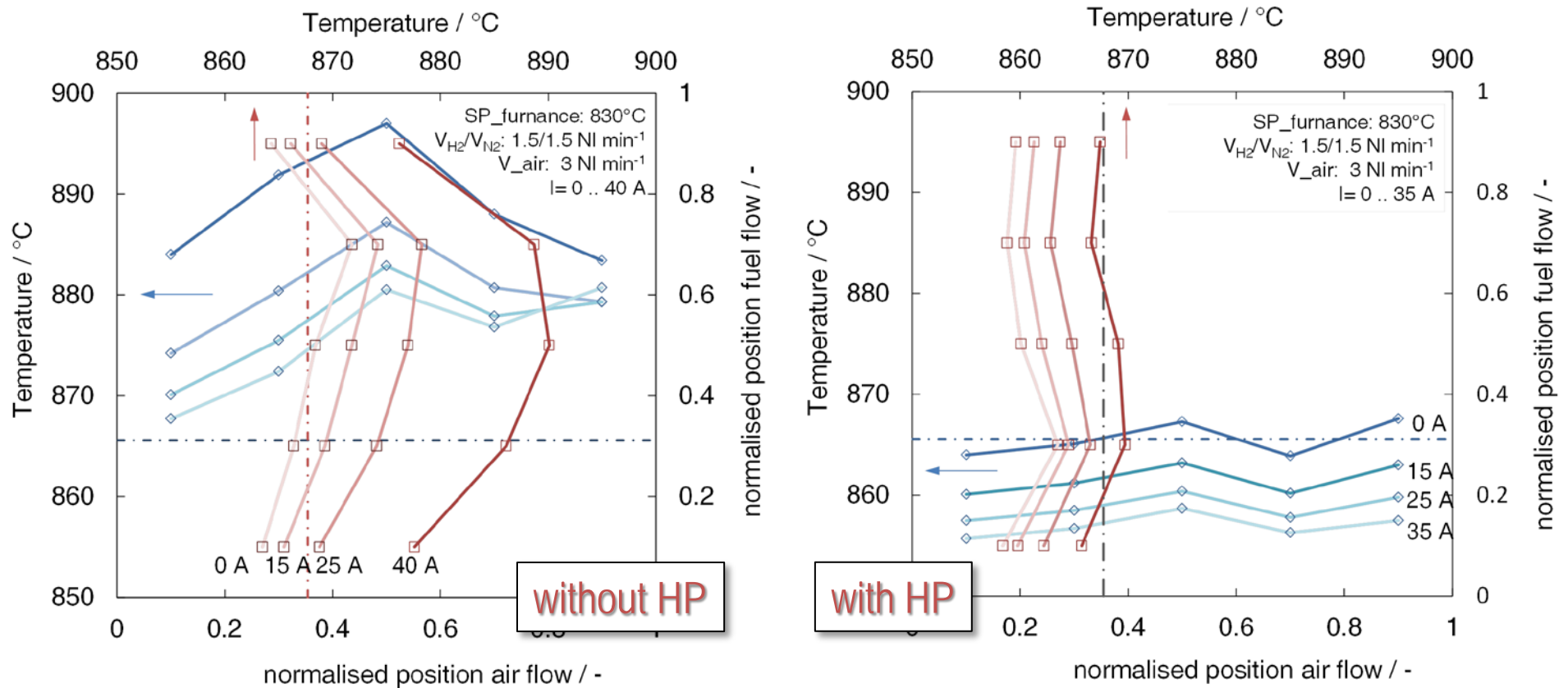
SOEC operation: 850°C, 90 g/h
 H₂O, 1.8 NI/min H₂, 3.0 NI/min Air

SOFC operation: 850°C, 1.5 NI/min
 H₂, 1.5 NI/min N₂, 3.0 NI/min Air

Results:

- Increase in heat pipe temperature shows thermal heat pipe integration
- Anode temperature is kept very close to heat pipe temperature

Shortstack tests with HP



Results:

→ Thermal integration of heat pipe

→ Isothermal temperature profiles for SOFC and SOEC operation

4. Conclusions



Conclusions

Summary

- I → Development of **planar heat pipe interconnectors**, stack integration
- II → Up to **1000 W** at isothermal operation, ($t=4\text{mm}$)
 - inert gas buffers, **H₂ buffers**
 - **capillary limit** for horizontal operation
- III → **Isothermal stack operation** in SOFC /SOEC
- IV

Outlook

- Temperature distributions in HP stacks under **dynamic operation** (start up behaviour)
- full scale stack layout & process integration

